

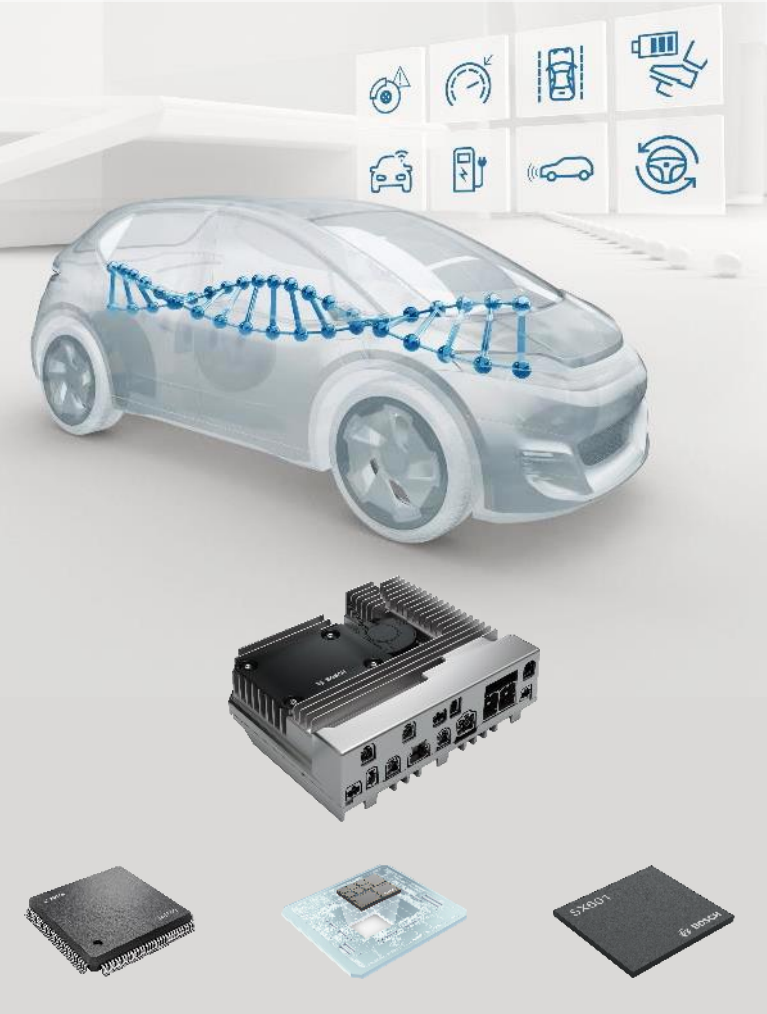


Trends in semiconductors for mobility

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Software-defined vehicle



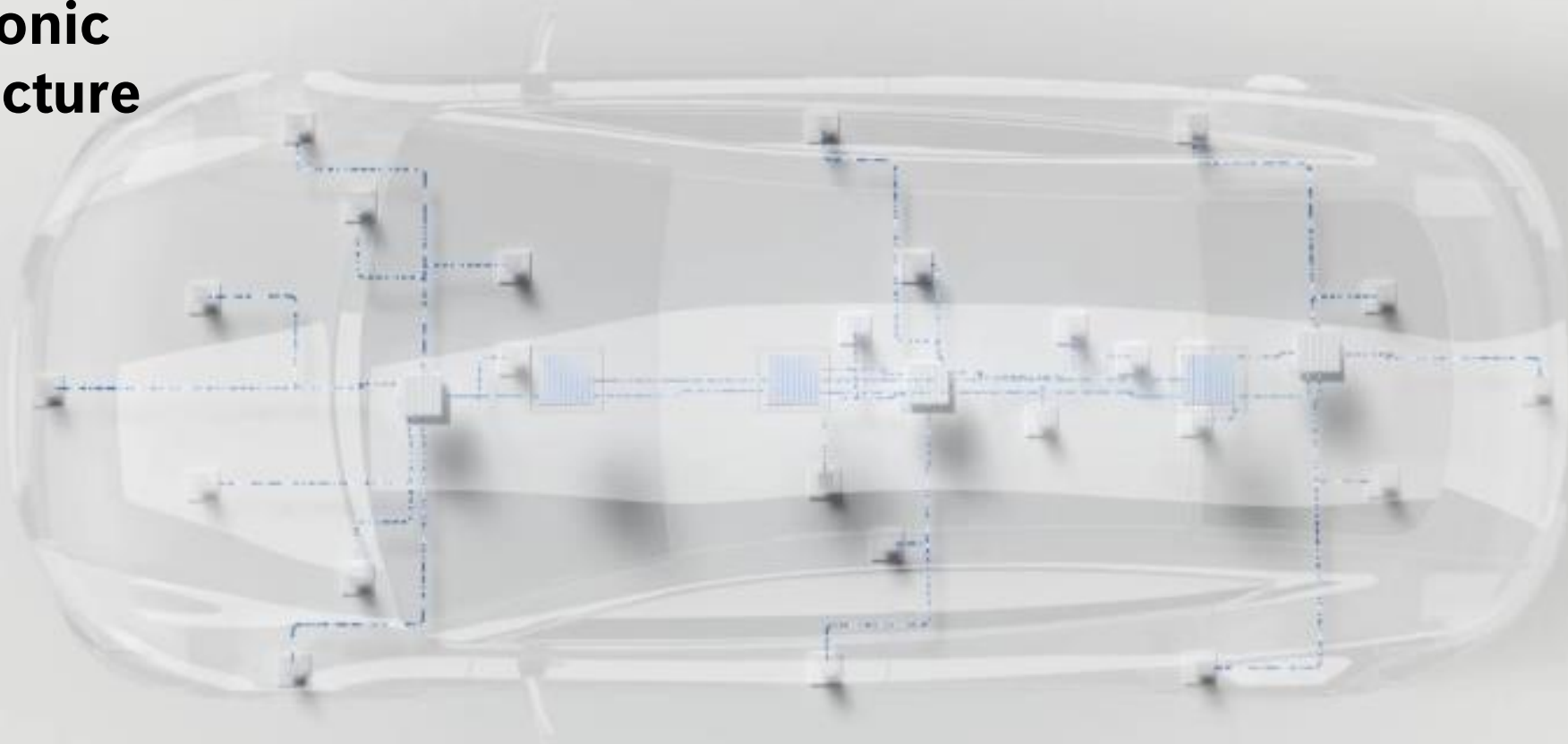
Electrification



Autonomous driving



Electric & Electronic Architecture



Electric & Electronic Architecture

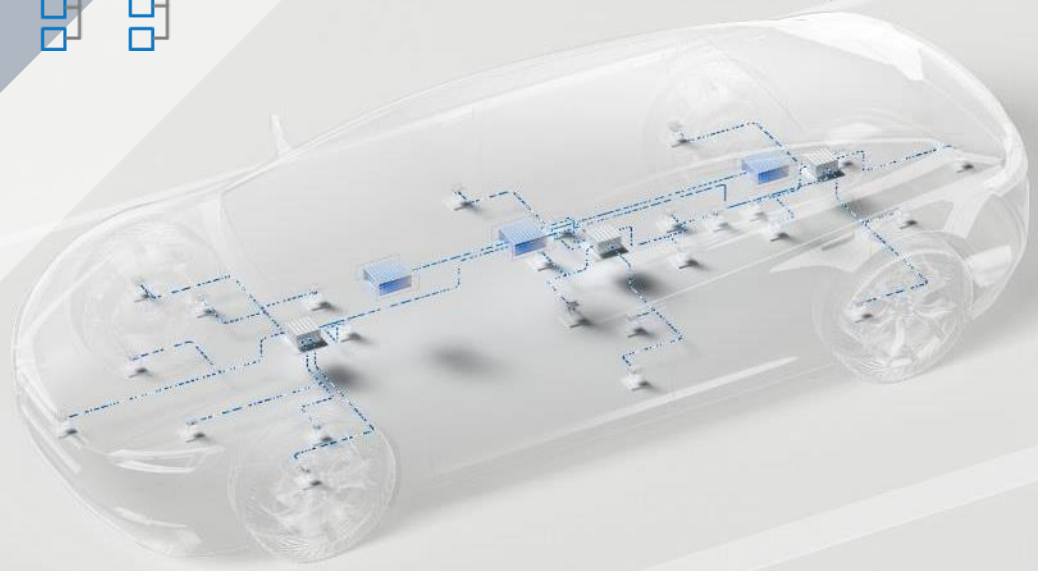
Vehicle-centralized



Domain-centralized



Distributed



Vehicle computers



Zone controllers



Sensors & actuators

Integration of software and I/O parts from fixed-location ECU (e.g., window control, ...)



Integration of dedicated hardware functionalities (e.g., body, climate, ...)



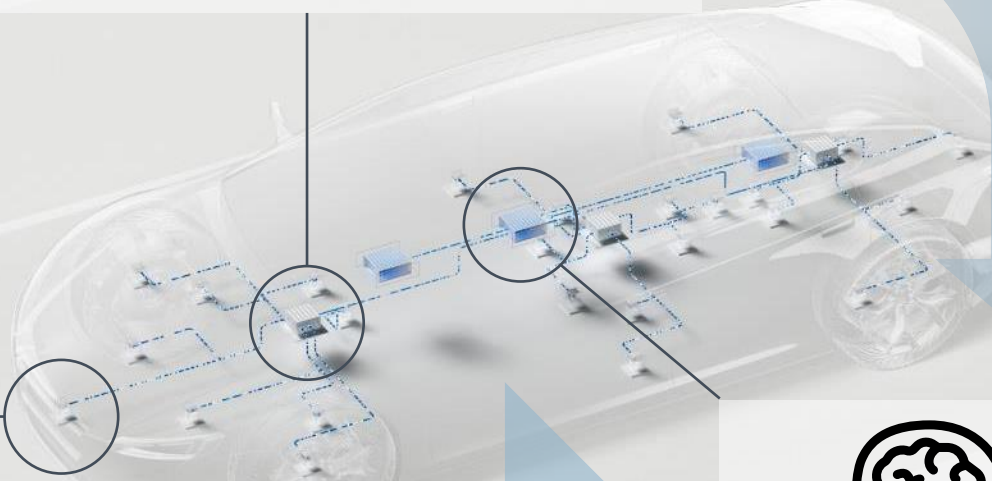
I/O connection of simple sensors and actuators (e.g., seat, window, ...)



Zone controllers



- SW Updates
- Hardware dependency
- Safety and homologation relevance



High-performance SW features that define vehicle-level functions (e.g., ADAS, ...)



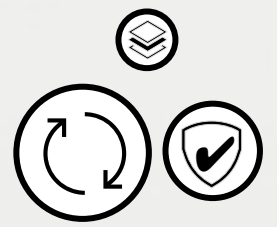
Sensors & actuators



I/O connection of high-data-rate sensors (e.g., camera streams, ...)



Vehicle computers







E/E integration



Supply chain



Safety



Security

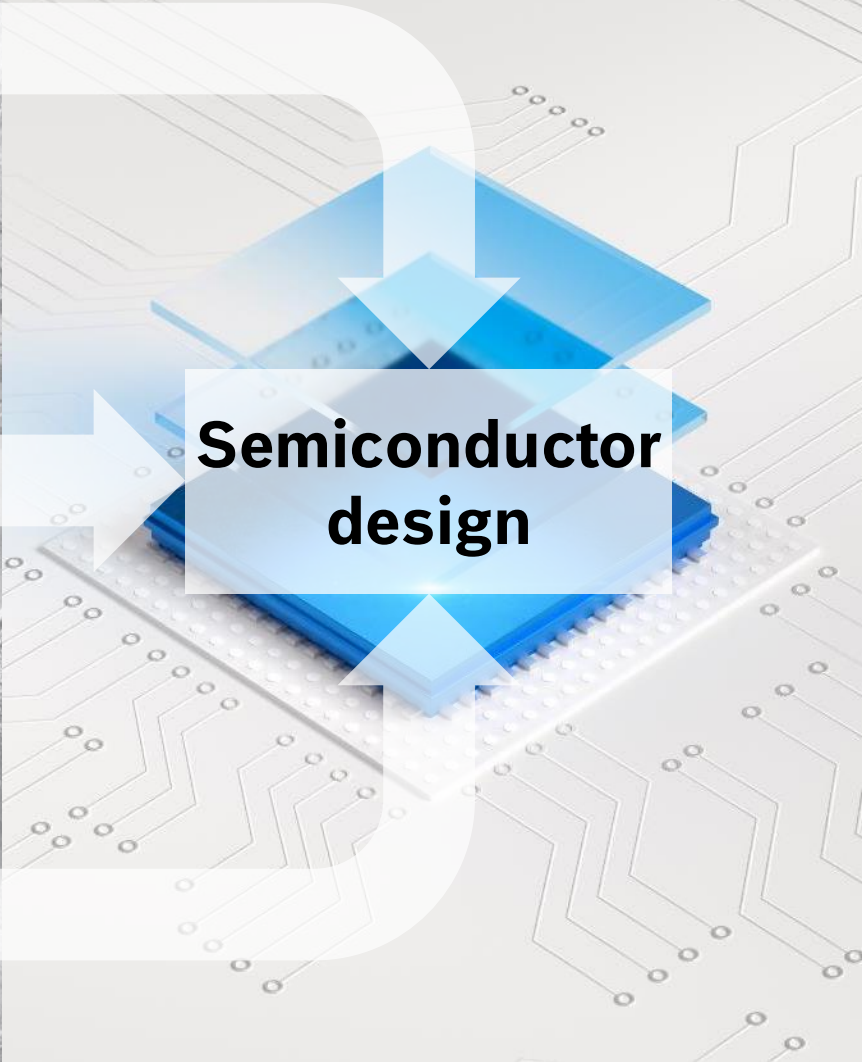


Scalability



Life cycles

**Mobility
specifics**



**Semiconductor
design**

The compute dilemma

PCB

Board-level integration

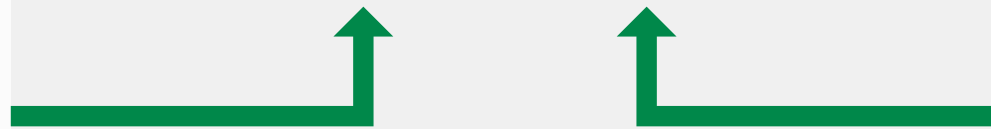
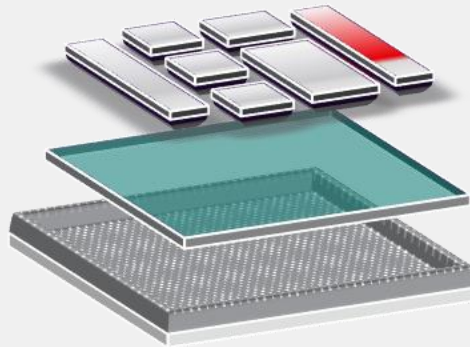


- Interconnect bandwidth & complexity
- Area consumption

- Functions in cost-optimized chips
- Exchangeability & scalability

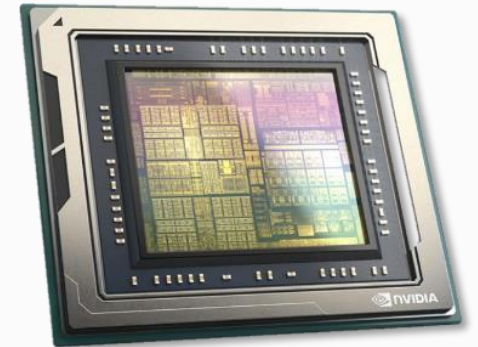
Chiplets

Package-level integration



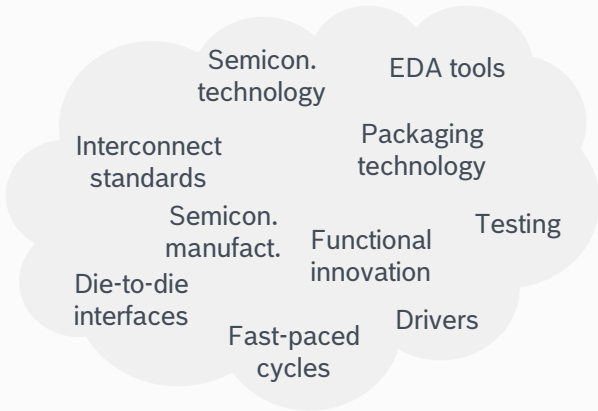
SoC

Chip-level integration

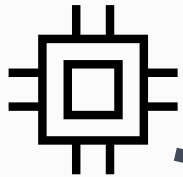


- High performance
- Dense integration
- Best efficiency

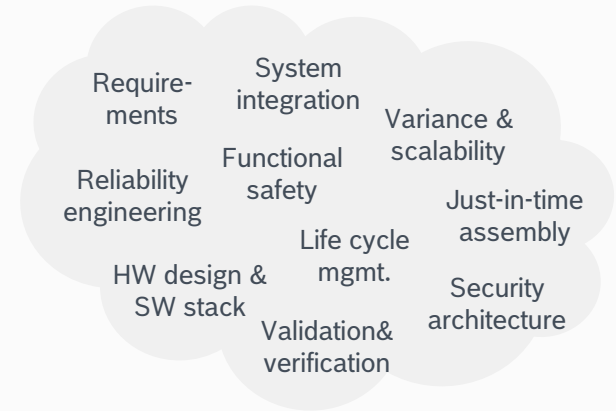
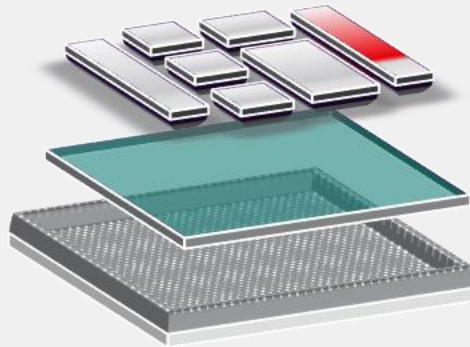
- Reticle size & yield
- R&D cost & TTM
- Single process node



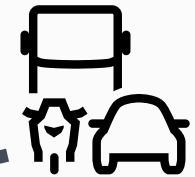
Capabilities of semiconductor industry



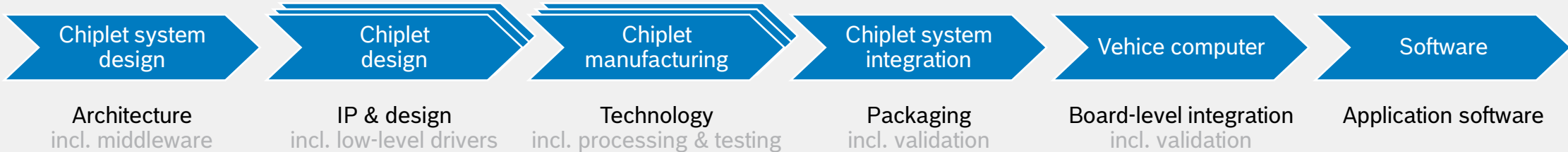
Automotive Chiplet Systems



Capabilities of mobility industry



Value chain



Vision: Open Ecosystem for Automotive Chiplet Systems

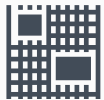
Key characteristics



Clearly defined
standards and
interfaces



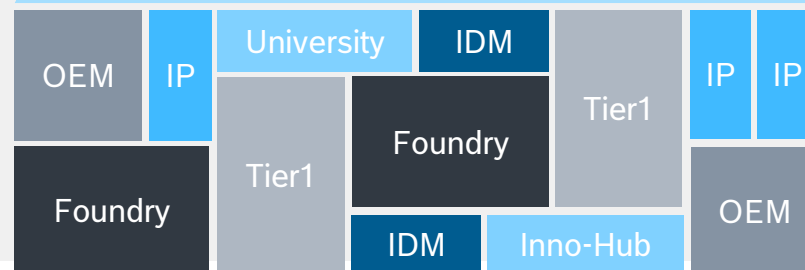
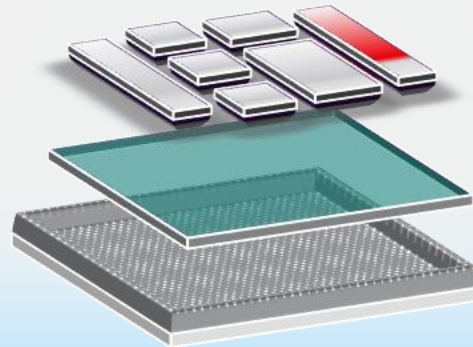
Multiple players
at each
value-chain step



Multi-vendor
integration of chiplets



Modular and
scalable architecture



Major benefits



Larger impact on
design decisions



More
design choices



Higher **flexibility**
"mix-and-match"



Differentiation
via tailored systems